



Product Change Notification / JAON-09TGWM044

Date:

17-Jan-2023

Product Category:

Analog Temperature Sensors, Analog to Digital Converters, Digital Potentiometers, Digital to Analog Converters

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5278 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP3421xxx, MCP3425Axx, MCP401xx, MCP402xx, MCP4706Axx, MCP4716Axx, MCP4725Axx, MCP4726Axx, MCP47DA1T, and MCP9510xx device families available in 6L SOT-23 package assembled at MMT assembly site.

Affected CPNs:

[JAON-09TGWM044_Affected_CPN_01172023.pdf](#)

[JAON-09TGWM044_Affected_CPN_01172023.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP3421xxx, MCP3425Axx, MCP401xx, MCP402xx, MCP4706Axx, MCP4716Axx, MCP4725Axx, MCP4726Axx, MCP47DA1T, and MCP9510xx device families available in 6L SOT-23 package assembled at MMT assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)
Wire Material	Au	CuPdAu
Die Attach Material	84-3J/8006NS	84-3J/8006NS
Molding Compound Material	G600V	G600V
Lead-Frame Material	CDA194	CDA194

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status:In Progress

Estimated First Ship Date:February 16, 2023 (date code: 2307)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	September 2022					->	January 2023					February 2023				
	3 6	3 7	3 8	3 9	4 0		1	2	3	4	5	6	7	8	9	10
Initial PCN Issue Date			X													
Qual Report Availability								X								
Final PCN Issue Date								X								
Estimated Implementation												X				

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Affected Catalog Part Numbers (CPN)

MCP4022T-202E/CH
MCP4022T-502E/CH
MCP4022T-103E/CH
MCP4022T-503E/CH
MCP4023T-202E/CH
MCP4023T-502E/CH
MCP4023T-103E/CH
MCP4023T-503E/CH
MCP4012T-202E/CH
MCP4012T-502E/CH
MCP4012T-103E/CH
MCP4012T-503E/CH
MCP4013T-202E/CH
MCP4013T-502E/CH
MCP4013T-103E/CH
MCP4013T-503E/CH
MCP9510CT-E/CH
MCP9510HT-E/CH
MCP9510HT-E/CHBAA
MCP3421A0T-E/CH
MCP3425A0T-E/CH
MCP3421LA0T-E/CH
MCP3421A1T-E/CH
MCP3425A1T-E/CH
MCP3421A2T-E/CH
MCP3425A2T-E/CH
MCP3421A3T-E/CH
MCP3425A3T-E/CH
MCP4706A0T-E/CH
MCP4706A1T-E/CH
MCP4706A2T-E/CH
MCP4706A3T-E/CH
MCP4716A0T-E/CH
MCP4716A1T-E/CH
MCP4716A2T-E/CH
MCP4716A3T-E/CH
MCP4726A0T-E/CH
MCP4726A1T-E/CH
MCP4726A2T-E/CH
MCP4726A3T-E/CH
MCP4725A0T-E/CH
MCP4725A1T-E/CH
MCP4725A2T-E/CH
MCP4725A3T-E/CH
MCP47DA1T-A0E/OT
MCP47DA1T-A1E/OT